## Features

- 200 W CW Incident Power @ $+85^{\circ} \mathrm{C}$
- Low Insertion Loss: <0.5 dB
- High Isolation: >40 dB
- Harmonics: <-70 dBc
- Operates from +V DC Bias Only
- Lead-Free 9 mm HQFN 20-lead Package
- Halogen-Free "Green" Mold Compound
- RoHS* Compliant and $260^{\circ} \mathrm{C}$ Reflow Compatible


## Description

The MASW-011040 is a high power PIN diode SP4T switch in a common anode configuration, operating from 50 MHz to 1 GHz . It features low insertion loss and excellent linearity. It includes two high-power ports capable of handling up to 200 Watts CW and two low-power ports capable of handling up to 100 Watts CW of incident power at a base plate temperature of $+85^{\circ} \mathrm{C}$.

This high power switch is ideal for use on land mobile radio and MIL-COM applications that require higher CW and pulsed power operation. This device can operate with positive-only DC supplies, making it suitable for switch-filter and power amplifier control circuits.

The MASW-011040 is manufactured using MACOM's hybrid manufacturing process featuring high voltage PIN diodes and passive devices integrated in a 9 mm HQFN 20 -lead plastic package.

The MASW-011040 is compatible with MACOM's MADR-010574 PIN Diode Driver.

## Ordering Information ${ }^{1}$

| Part Number | Package |
| :---: | :---: |
| MASW-011040-TR0500 | 500 pc reel |
| MASW-011040-001SMB | Sample Test Board |

[^0][^1]
## Functional Schematic



## Pin Configuration

| Pin | Function | Pin | Function |
| :---: | :---: | :---: | :---: |
| 1 | No Connection | 11 | Ground |
| $2^{2}$ | RF1 Input / V1 Bias | 12 | B4 Bias |
| 3 | No Connection | 13 | No Connection |
| 4 | B1 Bias | $14^{2}$ | RF4 Input / V4 Bias |
| 5 | Ground | 15 | No Connection |
| 6 | B2 Bias | 16 | Ground |
| $7^{2}$ | $\begin{aligned} & \text { RF2 Input / } \\ & \text { V2 Bias } \end{aligned}$ | 17 | No Connection |
| 8 | No Connection | 18 | RF Common / V5 Bias |
| $9^{2}$ | $\begin{aligned} & \text { RF3 Input / } \\ & \text { V3 Bias } \end{aligned}$ | 19 | No Connection |
| 10 | B3 Bias | 20 | Ground |
|  |  | Paddle ${ }^{3}$ | Ground |

2. RF1 and RF4 are high power ports ( 200 W ); RF2 and RF3 are low power ports (100 W).
3. The exposed paddle centered on the package bottom must be connected to RF, DC and thermal ground.

Electrical Specifications: $\mathrm{T}_{\mathrm{A}}=25^{\circ} \mathrm{C}, \mathrm{P}_{\mathrm{IN}}=0 \mathrm{dBm}$ (unless otherwise defined), $\mathrm{Z}_{0}=50 \Omega$
Bias $^{4}=5 \mathrm{~V} / 400 \mathrm{~mA}, 3 \mathrm{~V} / 200 \mathrm{~mA}, 100 \mathrm{~V} / 25 \mathrm{~mA}$

| Parameter | Test Conditions | Units | Min. | Typ. | Max. |
| :---: | :---: | :---: | :---: | :---: | :---: |
| $\begin{gathered} \text { Insertion Loss } \\ \text { RFC - RF1 \& RFC - RF4 } \end{gathered}$ | $\begin{aligned} & 0.5 \mathrm{GHz} \\ & 1.0 \mathrm{GHz} \end{aligned}$ | dB | - | $\begin{aligned} & 0.30 \\ & 0.45 \end{aligned}$ | $\overline{0.60}$ |
| $\begin{gathered} \text { Insertion Loss } \\ \text { RFC - RF2 \& RFC - RF3 } \end{gathered}$ | $\begin{aligned} & 0.5 \mathrm{GHz} \\ & 1.0 \mathrm{GHz} \end{aligned}$ | dB | - | $\begin{aligned} & 0.25 \\ & 0.40 \end{aligned}$ | $\overline{0.55}$ |
| $\begin{gathered} \text { Isolation } \\ \text { RFC - RF1 \& RFC - RF4 } \end{gathered}$ | $\begin{aligned} & 0.5 \mathrm{GHz} \\ & 1.0 \mathrm{GHz} \end{aligned}$ | dB | $\overline{40}$ | $\begin{aligned} & 51 \\ & 45 \end{aligned}$ | - |
| $\begin{gathered} \text { Isolation } \\ \text { RFC - RF2 \& RFC - RF3 } \end{gathered}$ | $\begin{aligned} & 0.5 \mathrm{GHz} \\ & 1.0 \mathrm{GHz} \end{aligned}$ | dB | - | $\begin{aligned} & 51 \\ & 45 \end{aligned}$ | - |
| Input Return Loss RFC-RF1 \& RFC - RF4 | $\mathrm{P}_{\text {IN }}=0 \mathrm{dBm}$ | dB | - | >13 | - |
| Input Return Loss RFC - RF2 \& RFC - RF3 | $\mathrm{P}_{\text {IN }}=0 \mathrm{dBm}$ | dB | - | >20 | - |
| CW Input Power RFC - RF1 \& RFC - RF4 | $85^{\circ} \mathrm{C}$ base plate, 550 MHz 950 MHz | dBm / W | - | $\begin{aligned} & 53 / 200 \\ & 52 / 158 \end{aligned}$ | - |
| CW Input Power RFC - RF2 \& RFC - RF3 | $85^{\circ} \mathrm{C}$ base plate, 550 MHz 950 MHz | dBm / W | - | $\begin{gathered} 50 / 100 \\ 49 / 80 \end{gathered}$ | - |
| $\begin{gathered} \mathrm{P} 0.1 \mathrm{~dB} \\ \text { RFC }- \text { RF1 \& RFC }- \text { RF4 } \end{gathered}$ | $85^{\circ} \mathrm{C}$ base plate, 550 MHz 950 MHz | dBm | - | $\begin{aligned} & 54 \\ & 53 \end{aligned}$ | - |
| $\begin{gathered} \mathrm{P} 0.1 \mathrm{~dB} \\ \text { RFC }-\mathrm{RF} 2 \& \mathrm{RFC}-\mathrm{RF} 3 \end{gathered}$ | $85^{\circ} \mathrm{C}$ base plate, 550 MHz 950 MHz | dBm | - | $\begin{aligned} & 51 \\ & 50 \end{aligned}$ | - |
| 2nd Harmonics | $\mathrm{P}_{\text {IN }}=49 \mathrm{dBm}, \mathrm{F}=950 \mathrm{MHz}$ | dBc | - | -75 | - |
| 3rd Harmonics | $\mathrm{P}_{\text {IN }}=49 \mathrm{dBm}, \mathrm{F}=950 \mathrm{MHz}$ | dBc | - | -85 | - |
| Ton, ${ }_{\text {OfF }}$ | (50\% CTL - 90\% RF and 10\% RF) 1 MHz Rep Rate in Modulating Mode | $\mu \mathrm{s}$ | - | 3.5 | - |
| $\mathrm{T}_{\text {RISE }}, \mathrm{T}_{\text {FALL }}$ | (10-90\% RF Voltage) <br> 1 MHz Rep Rate in Modulating Mode | $\mu \mathrm{s}$ | - | 0.8 | - |

[^2]
## Bias Table ${ }^{5}$

| RF State | V1 Bias <br> (V) | V2 Bias <br> (V) | V3 Bias <br> (V) | V4 Bias (V) | V5 Bias <br> (V) | B1 Bias <br> (V) | B2 Bias <br> (V) | B3 Bias (V) | B4 Bias (V) |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| RFC - RF1 Low Loss RFC - RF2 Isolation RFC - RF3 Isolation RFC - RF4 Isolation | $\begin{aligned} & 0 \vee @ \\ & 400 \mathrm{~mA} \end{aligned}$ | $\begin{gathered} 100 \text { V @ } \\ 25 \mathrm{~mA} \end{gathered}$ | $\begin{gathered} 100 \text { V @ } \\ 25 \mathrm{~mA} \end{gathered}$ | $\begin{gathered} 100 \mathrm{~V} @ \\ 25 \mathrm{~mA} \end{gathered}$ | $\begin{gathered} 5 \mathrm{~V} \text { @ } \\ 400 \mathrm{~mA} \end{gathered}$ | $\begin{gathered} 100 \text { V @ } \\ 0 \mathrm{~mA} \end{gathered}$ | $\begin{aligned} & 0 \mathrm{~V} @ \\ & 25 \mathrm{~mA} \end{aligned}$ | $\begin{aligned} & 0 \mathrm{~V} @ \\ & 25 \mathrm{~mA} \end{aligned}$ | $\begin{aligned} & 0 \mathrm{~V} @ \\ & 25 \mathrm{~mA} \end{aligned}$ |
| RFC - RF2 Low Loss <br> RFC-RF1 Isolation <br> RFC - RF3 Isolation <br> RFC - RF4 Isolation | $\begin{aligned} & 100 \text { V @ } \\ & 25 \mathrm{~mA} \end{aligned}$ | $\begin{aligned} & 0 \text { V @ } \\ & 200 \text { mA } \end{aligned}$ | $\begin{gathered} 100 \text { V @ } \\ 25 \mathrm{~mA} \end{gathered}$ | $\begin{gathered} 100 \mathrm{~V} @ \\ 25 \mathrm{~mA} \end{gathered}$ | $\begin{gathered} 3 \text { V @ } \\ 200 \text { mA } \end{gathered}$ | $\begin{aligned} & 0 \mathrm{~V} \text { @ } \\ & 25 \mathrm{~mA} \end{aligned}$ | $\begin{gathered} 100 \text { V @ } \\ 0 \mathrm{~mA} \end{gathered}$ | $\begin{aligned} & 0 \mathrm{~V} \text { @ } \\ & 25 \mathrm{~mA} \end{aligned}$ | $\begin{aligned} & 0 \mathrm{~V} \text { @ } \\ & 25 \mathrm{~mA} \end{aligned}$ |
| RFC - RF3 Low Loss RFC-RF1 Isolation RFC - RF2 Isolation RFC - RF4 Isolation | $\begin{aligned} & 100 \mathrm{~V} @ \\ & 25 \mathrm{~mA} \end{aligned}$ | $\begin{gathered} 100 \mathrm{~V} @ \\ 25 \mathrm{~mA} \end{gathered}$ | $\begin{gathered} 0 \text { V @ } \\ 200 \mathrm{~mA} \end{gathered}$ | $\begin{gathered} 100 \mathrm{~V} @ \\ 25 \mathrm{~mA} \end{gathered}$ | $\begin{gathered} 3 \text { V @ } \\ 200 \text { mA } \end{gathered}$ | $\begin{aligned} & 0 \mathrm{~V} \text { @ } \\ & 25 \mathrm{~mA} \end{aligned}$ | $\begin{aligned} & 0 \mathrm{~V} \text { @ } \\ & 25 \mathrm{~mA} \end{aligned}$ | $\begin{gathered} 100 \text { V @ } \\ 0 \mathrm{~mA} \end{gathered}$ | $\begin{aligned} & 0 \text { V @ } \\ & 25 \mathrm{~mA} \end{aligned}$ |
| RFC - RF4 Low Loss RFC - RF1 Isolation RFC - RF2 Isolation RFC - RF3 Isolation | $\begin{aligned} & 100 \mathrm{~V} @ \\ & 25 \mathrm{~mA} \end{aligned}$ | $\begin{gathered} 100 \mathrm{~V} @ \\ 25 \mathrm{~mA} \end{gathered}$ | $\begin{aligned} & 100 \text { V @ } \\ & 25 \mathrm{~mA} \end{aligned}$ | $\begin{gathered} 0 \vee @ \\ 400 \mathrm{~mA} \end{gathered}$ | $\begin{gathered} 5 \mathrm{~V} \text { @ } \\ 400 \mathrm{~mA} \end{gathered}$ | $\begin{aligned} & 0 \mathrm{~V} \text { @ } \\ & 25 \mathrm{~mA} \end{aligned}$ | $\begin{aligned} & 0 \mathrm{~V} \text { @ } \\ & 25 \mathrm{~mA} \end{aligned}$ | $\begin{aligned} & 0 \mathrm{~V} \text { @ } \\ & 25 \mathrm{~mA} \end{aligned}$ | $\begin{gathered} 100 \text { V @ } \\ 0 \mathrm{~mA} \end{gathered}$ |

5. DC reverse bias of a PIN diode operating at a high power is dependent on RF frequency, incident power, and VSWR. See Minimum Reverse DC Voltage table for high power operation.

## Absolute Maximum Ratings ${ }^{6,7}$

| Parameter | Absolute Maximum |
| :---: | :---: |
| Forward Current | +400 mA |
| Reverse DC Voltage | $\|-150 \mathrm{~V}\|$ |
| Operating Temperature | $-55^{\circ} \mathrm{C}$ to $+85^{\circ} \mathrm{C}$ |
| Storage Temperature | $-65^{\circ} \mathrm{C}$ to $+150^{\circ} \mathrm{C}$ |
| Junction Temperature | $+175^{\circ} \mathrm{C}$ |

6. Exceeding any one or combination of these limits may cause permanent damage to this device.
7. MACOM does not recommend sustained operation near these survivability limits.

Minimum Reverse DC Voltage ${ }^{8}$

| Frequency (MHz) | Minimum Reverse <br> DC Voltage |
| :---: | :---: |
| 50 | $\|-142 \mathrm{~V}\|$ |
| 100 | $\|-102 \mathrm{~V}\|$ |
| 200 | $\|-60 \mathrm{~V}\|$ |
| 500 | $\|-26 \mathrm{~V}\|$ |
| 1000 | $\|-13 \mathrm{~V}\|$ |

8. Required to maintain low loss under 200 W of incident power with 1.5:1 VSWR.

## Typical Performance Curves:

## Insertion Loss



Isolation RFC - RF1


Isolation RFC - RF3


## Return Loss



Isolation RFC - RF2


Isolation RFC - RF4


## Application Schematic



## Off-Chip Component Values

| Component | Value |
| :---: | :---: |
| $\mathrm{C} 1, \mathrm{C} 3, \mathrm{C} 6, \mathrm{C} 8, \mathrm{C} 9$ | 1000 pF |
| $\mathrm{C} 2, \mathrm{C} 4, \mathrm{C} 5, \mathrm{C} 7, \mathrm{C} 10$ | 270 pF |
| $\mathrm{L} 1-\mathrm{L} 5$ | 520 nH |
| $\mathrm{R} 1-\mathrm{R} 4$ | $4.4 \mathrm{k} \Omega$ |
| $\mathrm{R5}^{9}$ | $10 \Omega$ |

9. Must be rated for appropriate power handling.

## Handling Procedures

Please observe the following precautions to avoid damage:

## Static Sensitivity

These electronic devices are sensitive to electrostatic discharge (ESD) and can be damaged by static electricity. Proper ESD control techniques should be used when handling these Class 1B HBM devices.

Lead Free 9 mm HQFN 20-Lead ${ }^{\dagger}$


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[^0]:    1. Reference Application Note M513 for reel size information.
[^1]:    *Restrictions on Hazardous Substances,
    European Union Directive 2011/65/EU.

[^2]:    4. See Bias table.
[^3]:    ${ }^{\dagger}$ Reference Application Note S2083 for lead-free solder reflow recommendations.
    Meets JEDEC moisture sensitivity level 3 requirements.
    Plating is NiPdAuAg.

